



Material Content Data Sheet



Sales Product Name	TLE9261QX			Issued	24. January 2018			
MA#	MA001659954							
Package	PG-VQFN-48-31			Weight*	129.39 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.471	1.91	1.91	19100	19100
leadframe	inorganic material	phosphorus	7723-14-0	0.018	0.01		138	
	non noble metal	zinc	7440-66-6	0.072	0.06		554	
	non noble metal	iron	7439-89-6	1.433	1.11		11076	
wire	non noble metal	copper	7440-50-8	58.193	44.97	46.15	449750	461518
	non noble metal	copper	7440-50-8	0.552	0.43	0.43	4263	4263
	encapsulation	organic material	carbon black	1333-86-4	0.188	0.15		1453
	plastics	epoxy resin	-	7.958	6.15		61505	
	inorganic material	silicondioxide	60676-86-0	54.516	42.13	48.43	421332	484290
leadfinish	non noble metal	tin	7440-31-5	2.596	2.01	2.01	20066	20066
plating	noble metal	silver	7440-22-4	0.614	0.47	0.47	4744	4744
glue	plastics	epoxy resin	-	0.179	0.14		1384	
	noble metal	silver	7440-22-4	0.600	0.46	0.60	4635	6019
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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